

Erratum

Effect of Time-Temperature Path of Cure on the Water Absorption of High T_g Epoxy Resins

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Correct Table VII:

TABLE VII
Comparison of Studies of Extent of Cure on Water Absorption in Epoxy Resins^a

Property	System	DER337/TMAB ^b XD/TMAB ^b	TGDDM/ DDS ^c	TGDDM/ DDS ^d	Epon 828/ <i>m</i> -PD/aniline ^e
As T_g (or extent of cure)		↑	↑	↑	↑
RT M_∞		↑	↑	↓	↑
RT ρ		↓	—	—	↑
RT D		↓	—	↓	↑

^aKey: ↑ = increases; ↓ = decreases; — = not reported.

^bPresent study.

^cRef. 61.

^dRef. 33.

^eRef. 5.

Page 3593, caption for Fig. 3(b) should read:

Fig. 3(b). Isothermal time-temperature-transformation (TTT) cure diagram of XD7342/TMAB: temperature of cure vs. times to gelation (■) and vitrification (○); (····) $T_{g\infty}$.

Page 3595, paragraph 3, line 6 should read:

material in molds for 100°C for 10 min; place molds in oven at preset

Page 3595, paragraph 4, line 10 should read:

4000 h. The equilibrium values of the moisture gains (M_∞) vs. RH are